

MOS FIELD EFFECT TRANSISTOR **2SK2488**

SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

DESCRIPTION

The 2SK2488 is N-Channel MOS Field Effect Transistor designed for high voltage switching applications.

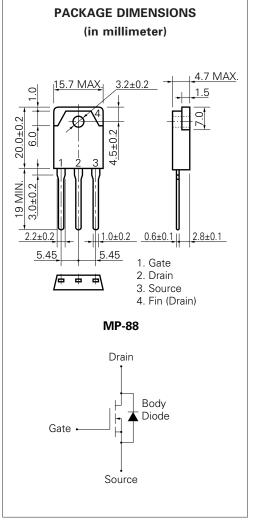
FEATURES

- Low On-Resistance
- RDS (on) = 1.2 Ω (VGS = 10 V, ID = 5.0 A)
- Low C_{iss} $C_{iss} = 2 900 \text{ pF TYP}.$
- High Avalanche Capability Ratings

ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Drain to Source Voltage	VDSS	900	V
Gate to Source Voltage	Vgss	±30	V
Drain Current (DC)	D (DC)	±10	А
Drain Current (pulse)*	D (pulse)	±20	А
Total Power Dissipation (T _c = 25 $^{\circ}$ C)	Ρτ1	150	W
Total Power Dissipation (T _A = 25 $^{\circ}$ C)	Рт2	3.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg -55	5 to +150	°C
Single Avalanche Current**	las	10	А
Single Avalanche Energy**	Eas	294	mJ
* PW \leq 10 μ s, Duty Cycle \leq 1 %			

** Starting T_{ch} = 25 °C, R_G = 25 Ω , V_{GS} = 20 V \rightarrow 0

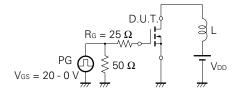


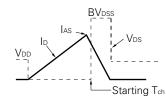
ELECTRICAL CHARACTERISTICS (TA = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain to Source On-Resistance	RDS (on)		1.0	1.2	Ω	$V_{GS} = 10 \text{ V}, \text{ Id} = 5.0 \text{ A}$
Gate to Source Cutoff Voltage	VGS (off)	2.5		3.5	V	V _{DS} = 10 V, I _D = 1 mA
Forward Transfer Admittance	y _{fs}	3.5			S	$V_{DS} = 20 V, I_{D} = 5.0 A$
Drain Leakage Current	Ibss			100	μA	$V_{DS} = V_{DSS}, V_{GS} = 0$
Gate to Source Leakage Current	Igss			±100	nA	$V_{GS} = \pm 30 \text{ V}, \text{ V}_{DS} = 0$
Input Capacitance	Ciss		2 900		pF	V _{DS} = 10 V
Output Capacitance	Coss		400		pF	V _{GS} = 0
Reverse Transfer Capacitance	Crss		70		pF	f = 1 MHz
Turn-On Delay Time	td (on)		35		ns	ID = 5.0 A
Rise Time	tr		30		ns	Vgs = 10 V
Turn-Off Delay Time	td (off)		160		ns	V _{DD} = 150 V
Fall Time	tr		32		ns	$R_G = 10 \Omega$
Total Gate Charge	QG		90		nC	ID = 10 A
Gate to Source Charge	Q _{GS}		16		nC	V _{DD} = 450 V
Gate to Drain Charge	Qgd		40		nC	Vgs = 10 V
Body Diode Forward Voltage	VF (S-D)		1.0		V	IF = 10 A, VGS = 0
Reverse Recovery Time	trr		990		ns	IF = 10 A, VGS = 0
Reverse Recovery Charge	Qrr		7.0		μC	di/dt = 50 A/µs

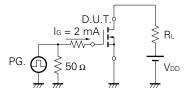
Test Circuit 1 Avalanche Capability

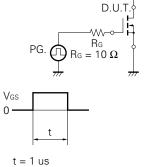
Test Circuit 2 Switching Time



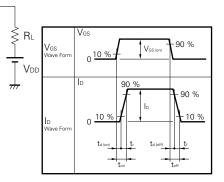


Test Circuit 3 Gate Charge

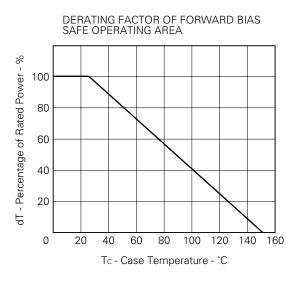




Duty Cycle $\leq 1 \%$

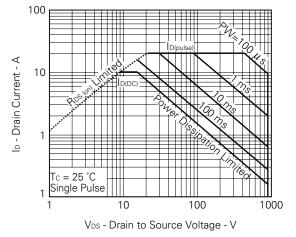


The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

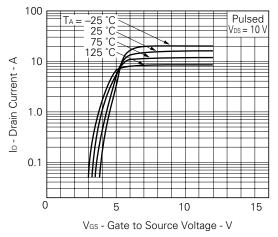


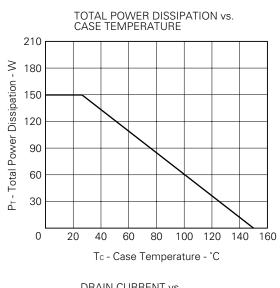
TYPICAL CHARACTERISTICS (TA = 25 °C)



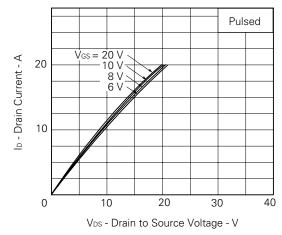


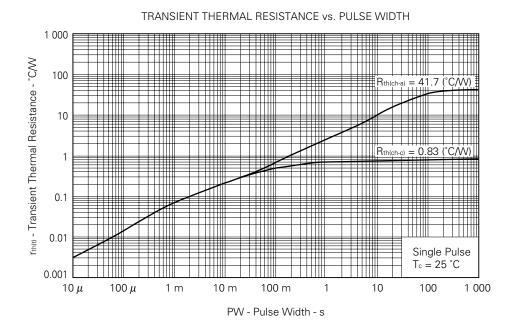
FORWARD TRANSFER CHARACTERISTICS



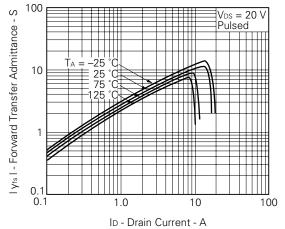


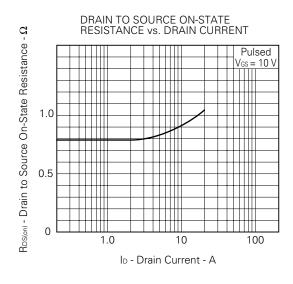
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



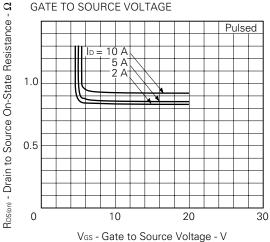


FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

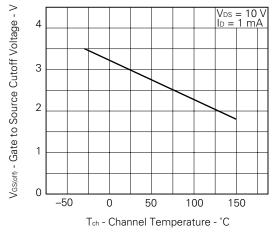


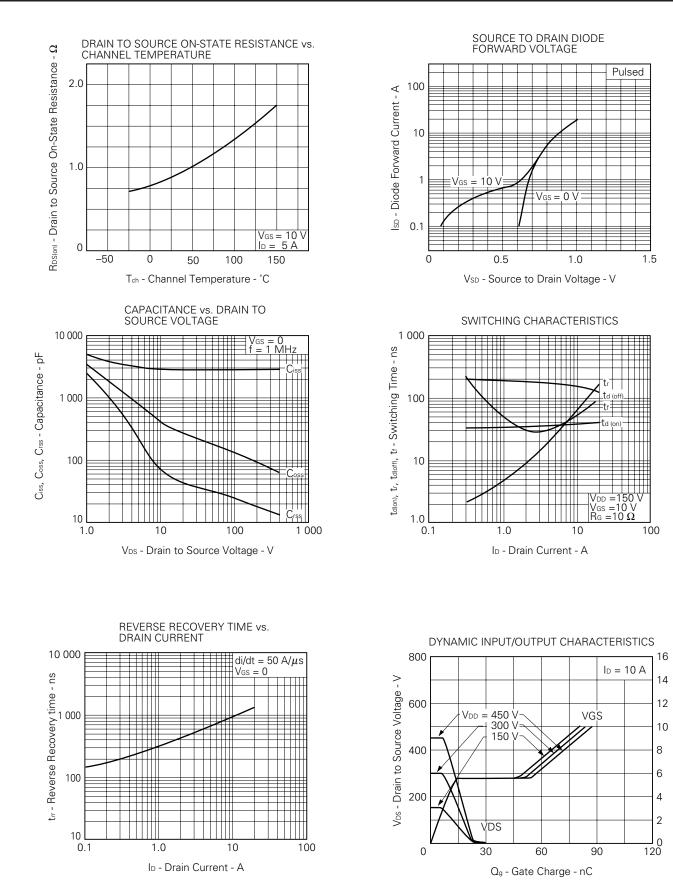


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

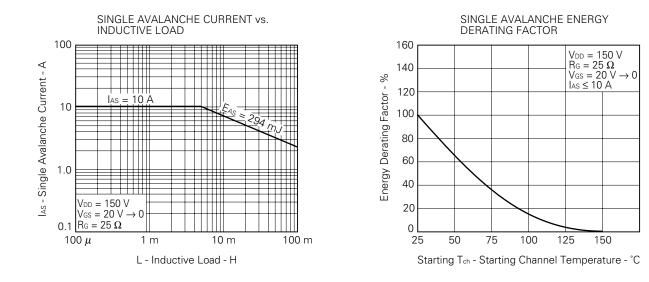


GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE





V_{GS} - Gate to Source Voltage - V



REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

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